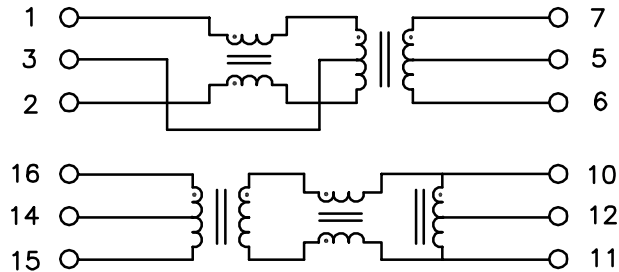


DIMENSIONS : Inch [mm]  
CO-PLANARITY : 0.004 [0.10]



**PART NO. : TG22-S143NDRL**

16PIN SMT ISOLATION MODULE FOR 10/100BASE-TX  
IEEE802.3u APPLICATIONS

LEAD-FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS  
CONDITION PER IPC/JEDEC J-STD-020C

OPERATING TEMPERATURE 0/+70°C

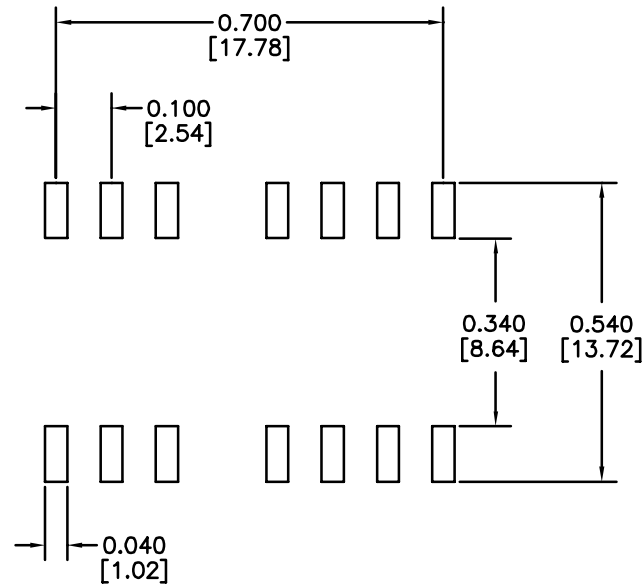
**ELECTRICAL SPECIFICATIONS @25° C**

TURN RATIO	
TX P16-15:P10-11	1CT:1.41CT±3%
RX P1-2:P7-6	1CT:1CT±3%
OCL (100KHz,0.1Vrms,8mA)	
P7-6,P10-11	350µH min
DCR P7-6,P16-15	0.9Ω max
LL P1-2,P16-15	0.4µH max
Cw/w	20pF typ
CROSSTALK 0.1-100MHz	-40dB typ
CMR 0.1-100MHz	-40dB typ
ISOLATION	1,500Vrms

**HALO/PBL**

CALIFORNIA, USA  
KOWLOON, HONG KONG  
SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
FOR	FAST ETHERNET		DRAWN	PETER LU	4/28/05	A	
PART NO.	TG22-S143NDRL		CHECKED				
SCALE	NONE	PAGE	1 OF 2	APPROVED			
				FILE	S143NDRL.DWG		



RECOMMENDED SOLDER PAD DIMENSIONS  
 DIMENSIONS: Inch [mm]

<b>HALO/PBL</b>	TITLE ISOLATION MODULE		SIGNATURES		DATE	REV.	DESC.	DATE
	FOR FAST ETHERNET		DRAWN PETER LU		4/28/05	A		
	PART NO. TG22-S143NDRL		CHECKED					
	SCALE NONE		PAGE 2 OF 2		APPROVED			
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE		FILE S143NDRL.DWG						